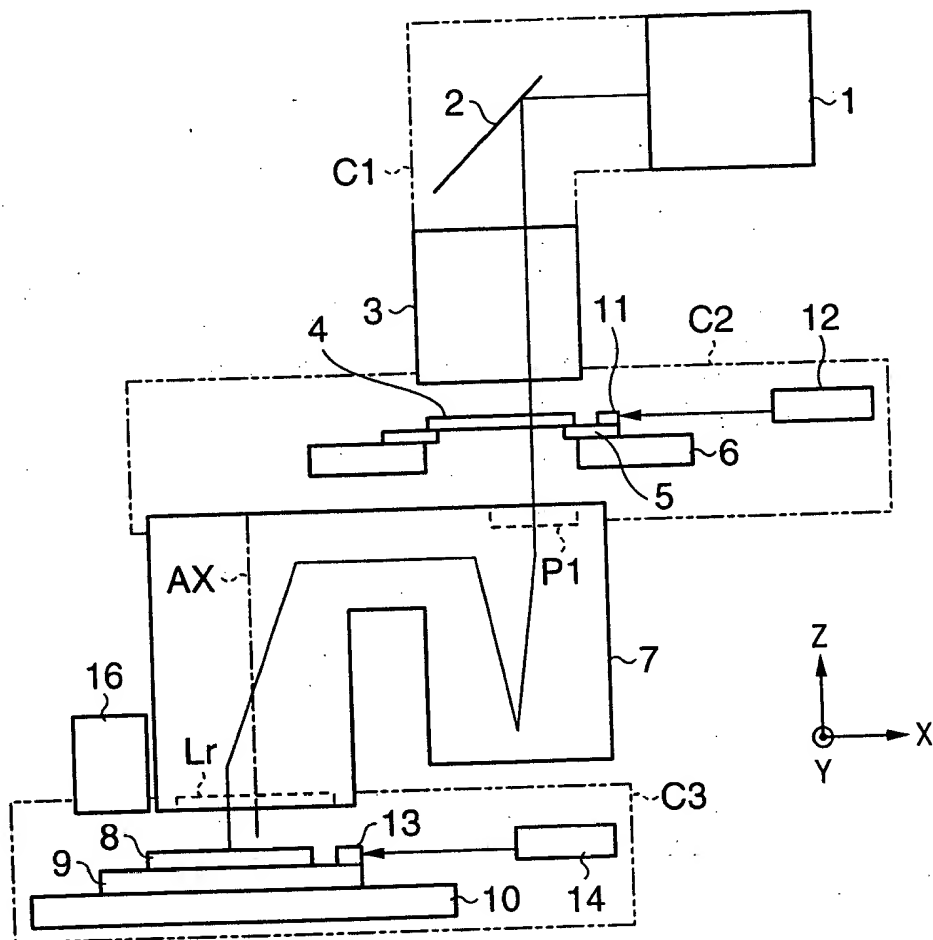


FIG. 1



00000000-11301

FIG. 2B

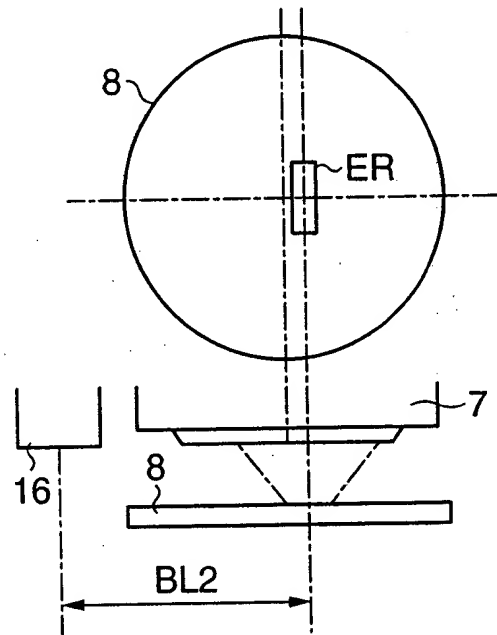


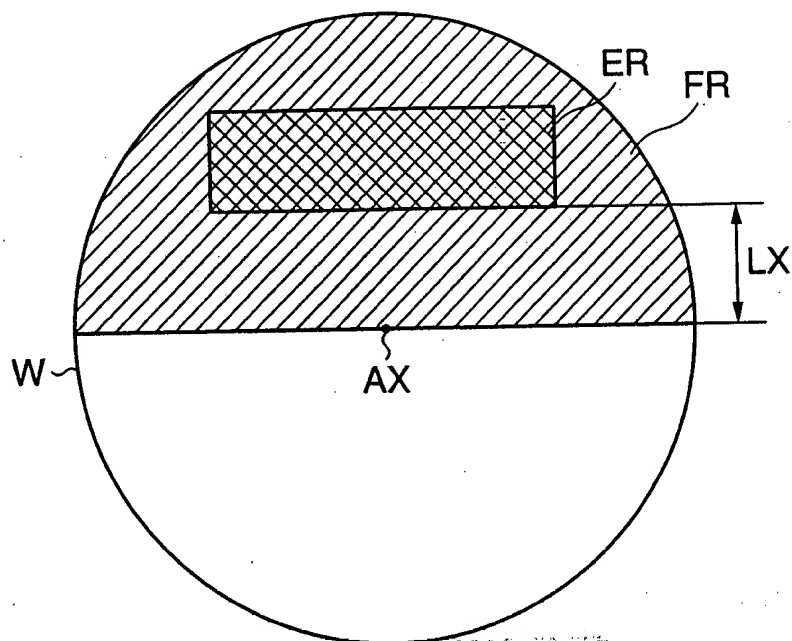
FIG. 3

FIG. 4

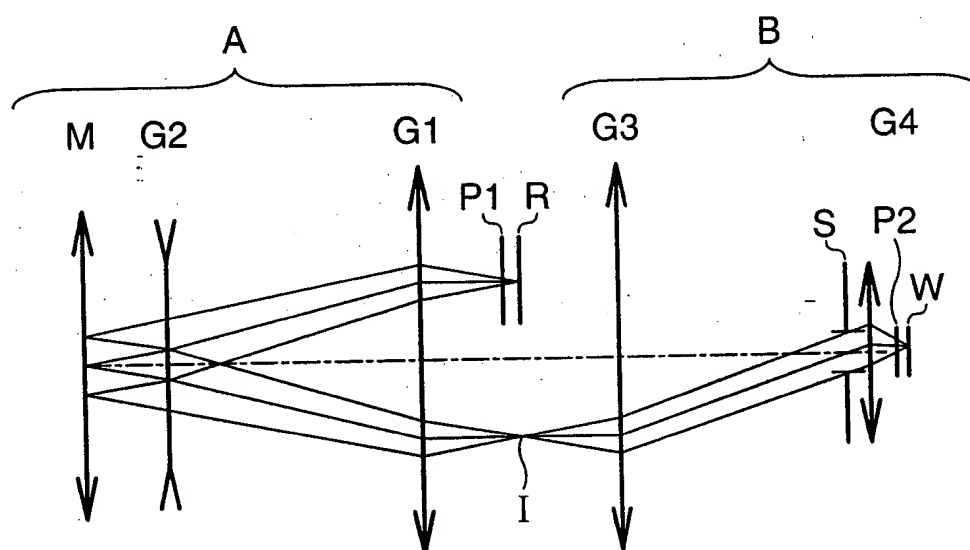
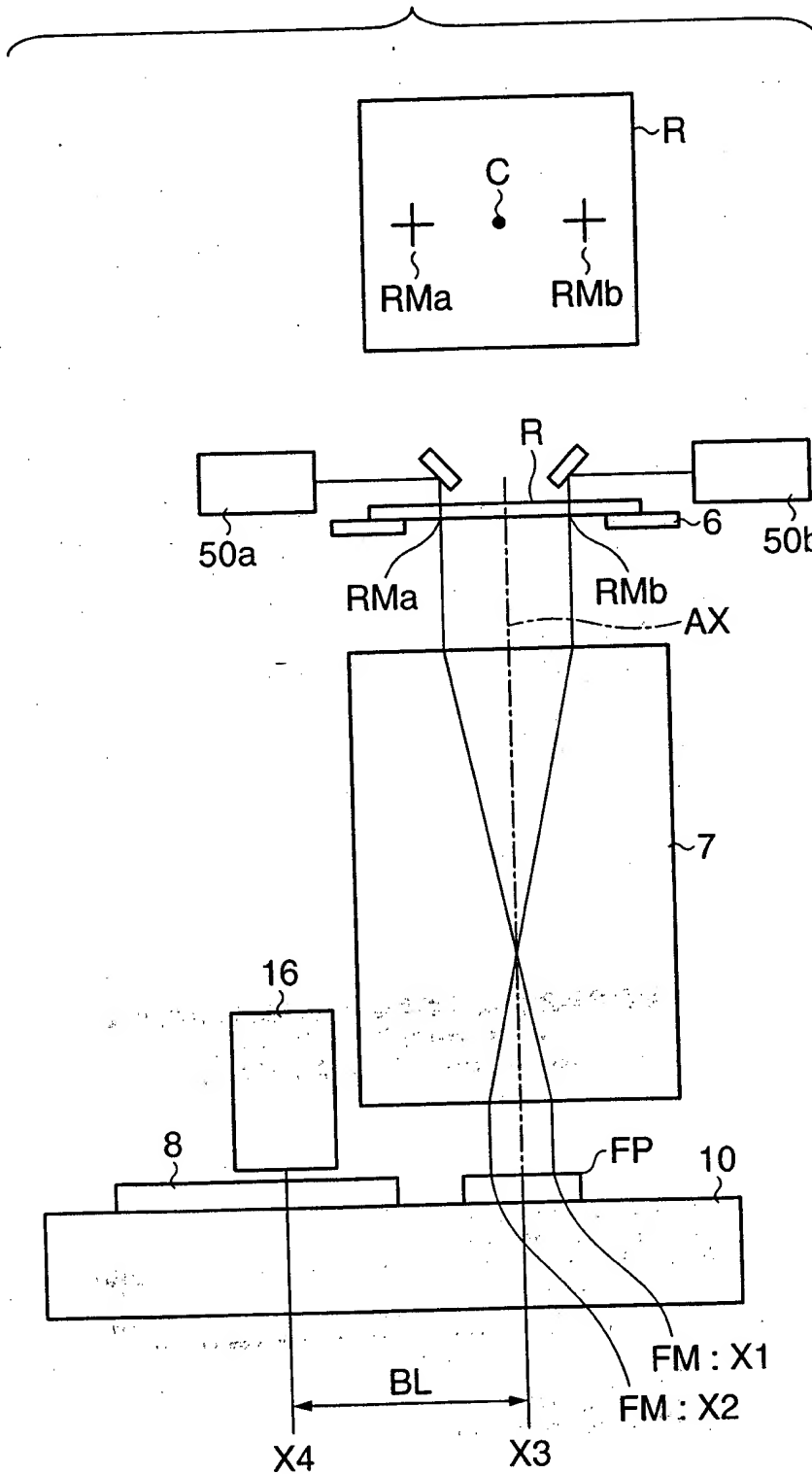


FIG. 5



000000-1101

TOEFT-85098000

FIG. 6

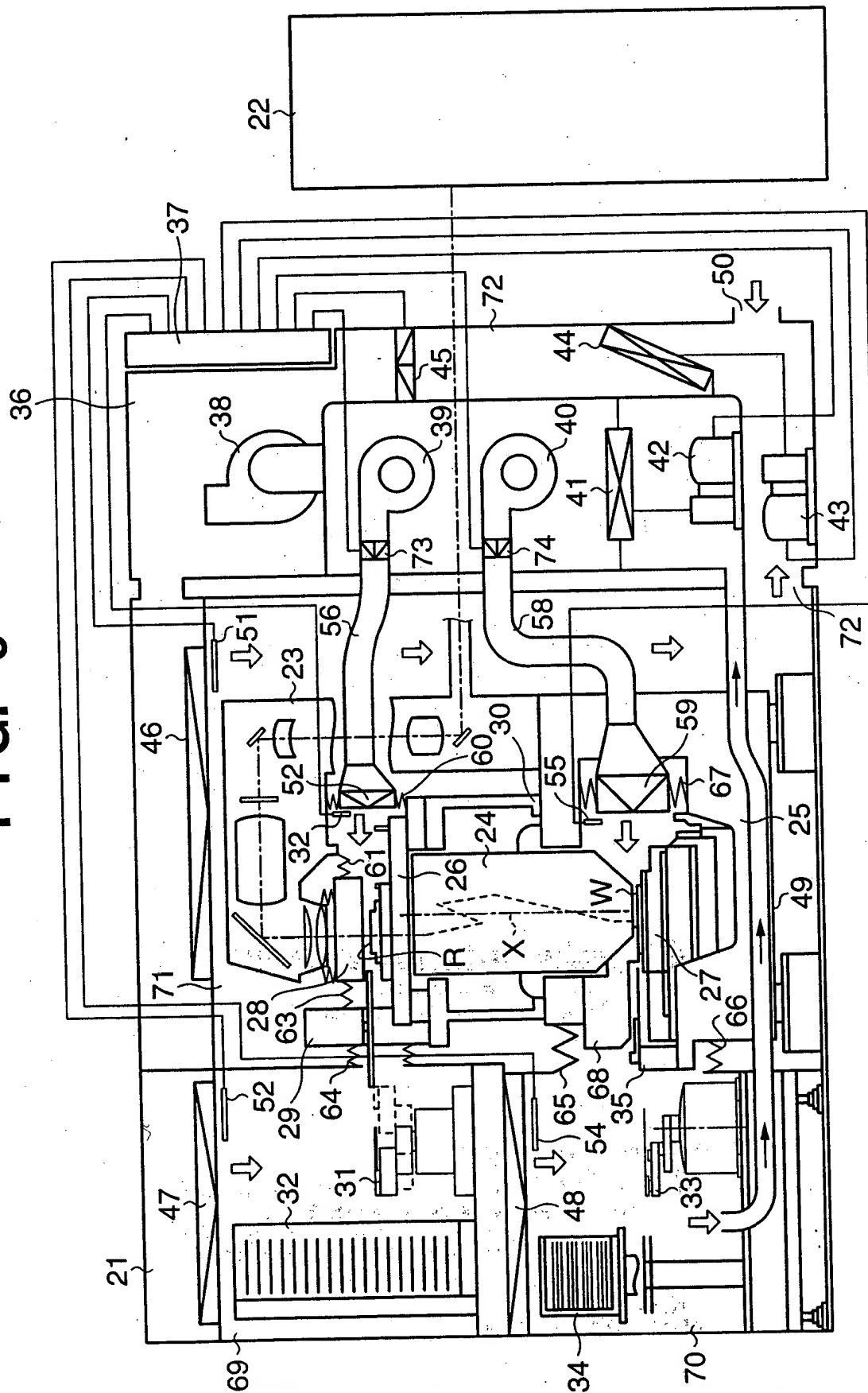
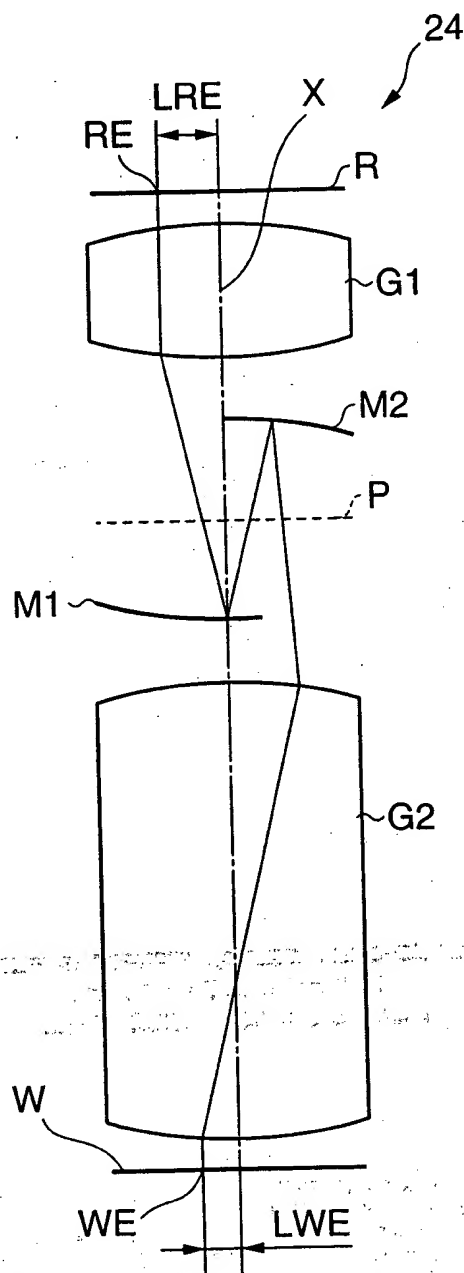


FIG. 7



10244-0509000

9/15

FIG. 9A

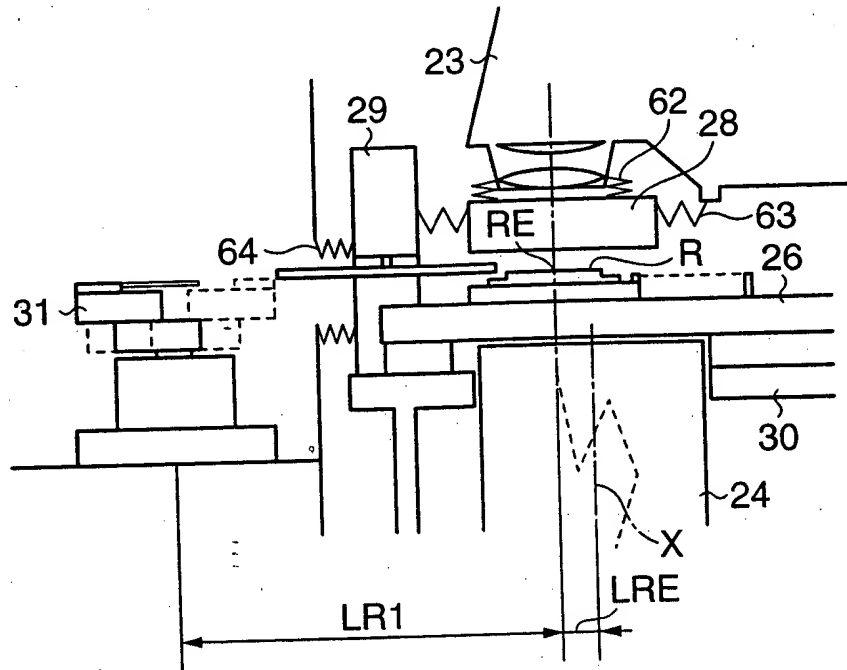


FIG. 9B

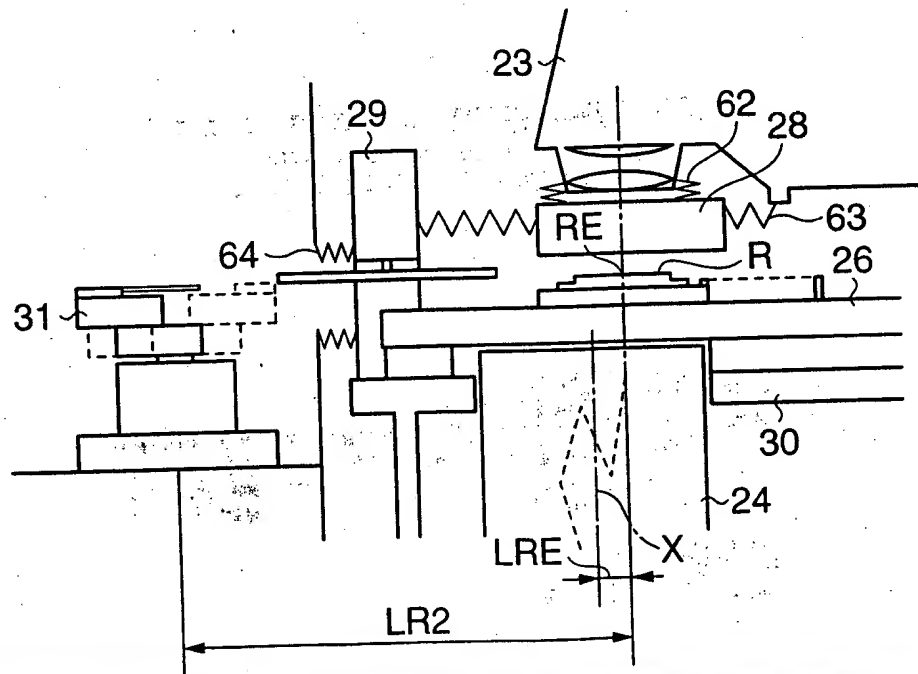


FIG. 10A

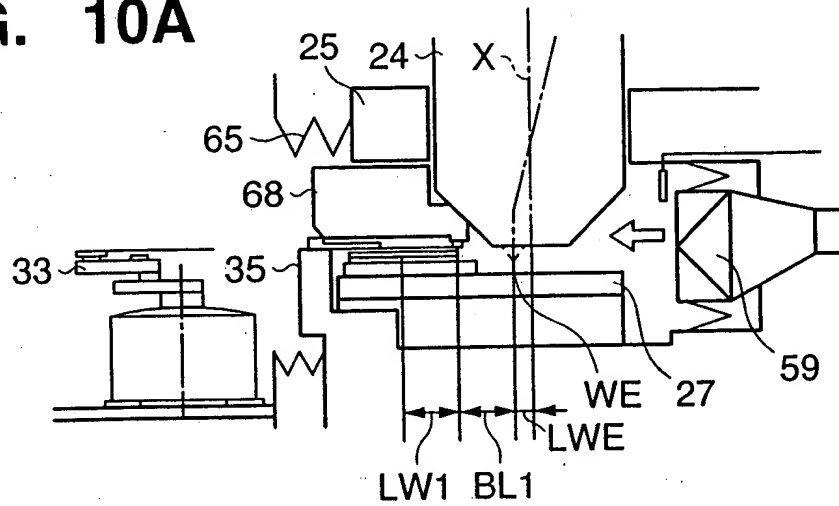


FIG. 10B

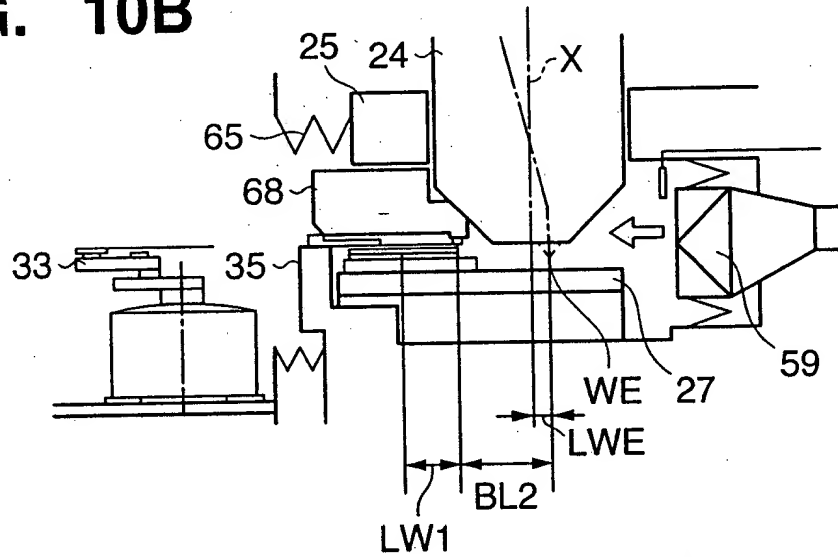


FIG. 10C

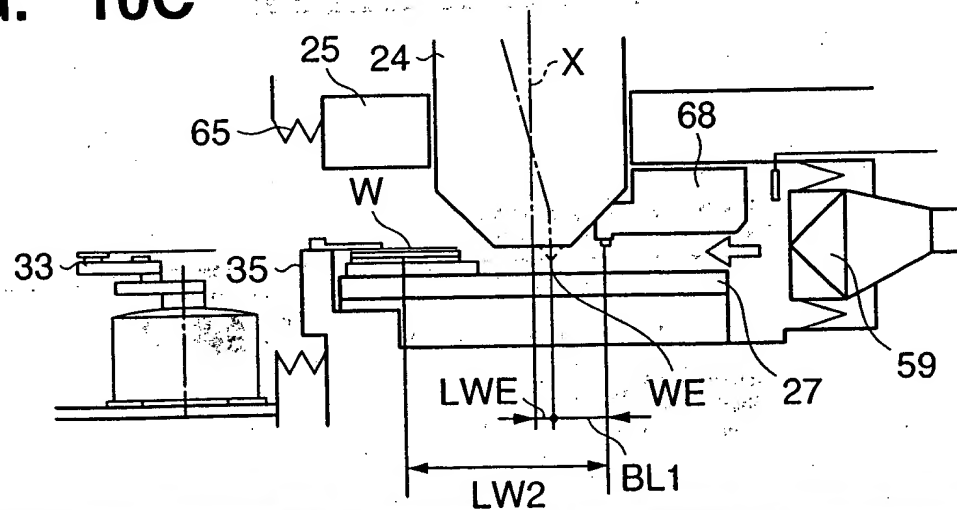


FIG. 10A

FIG. 11

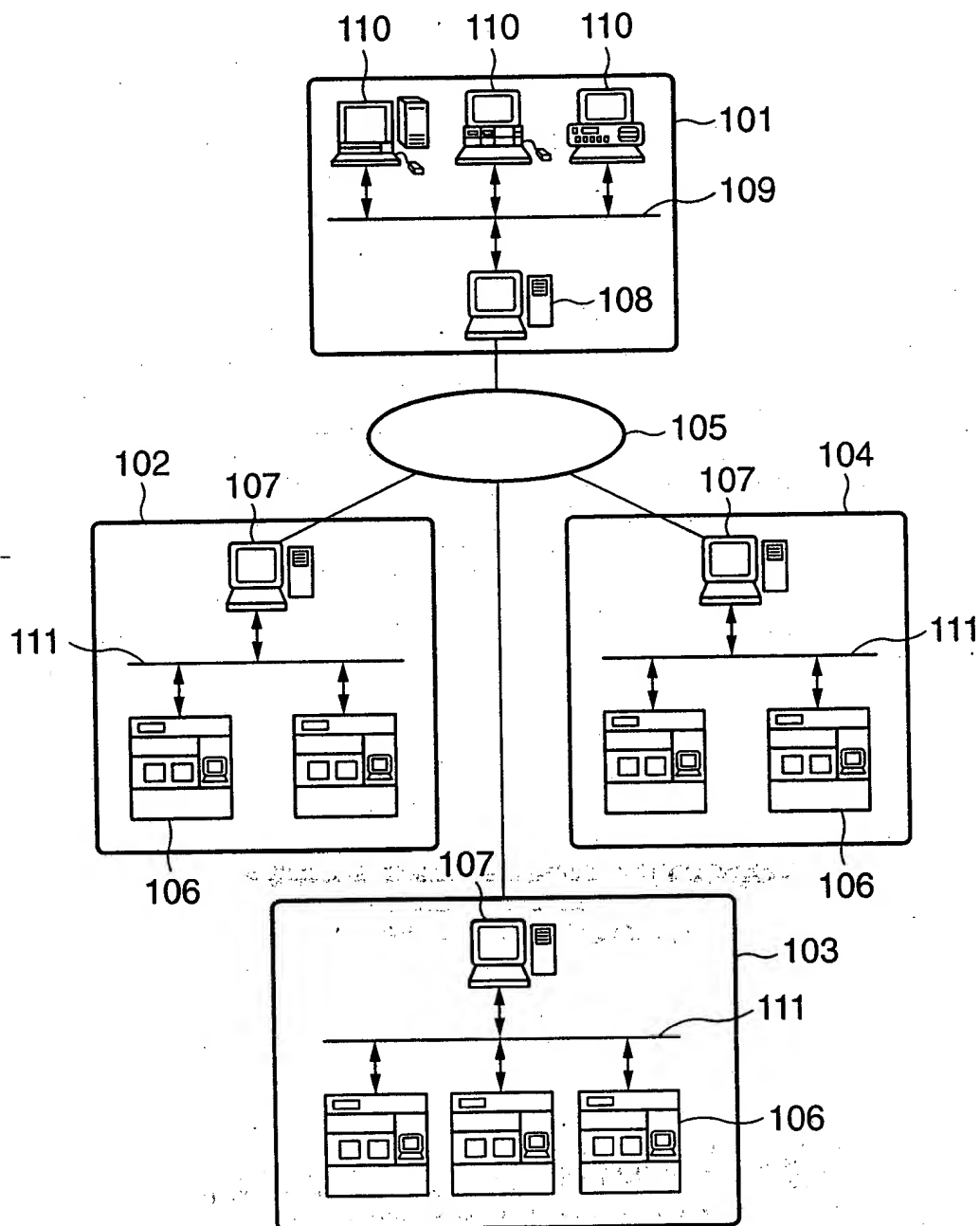
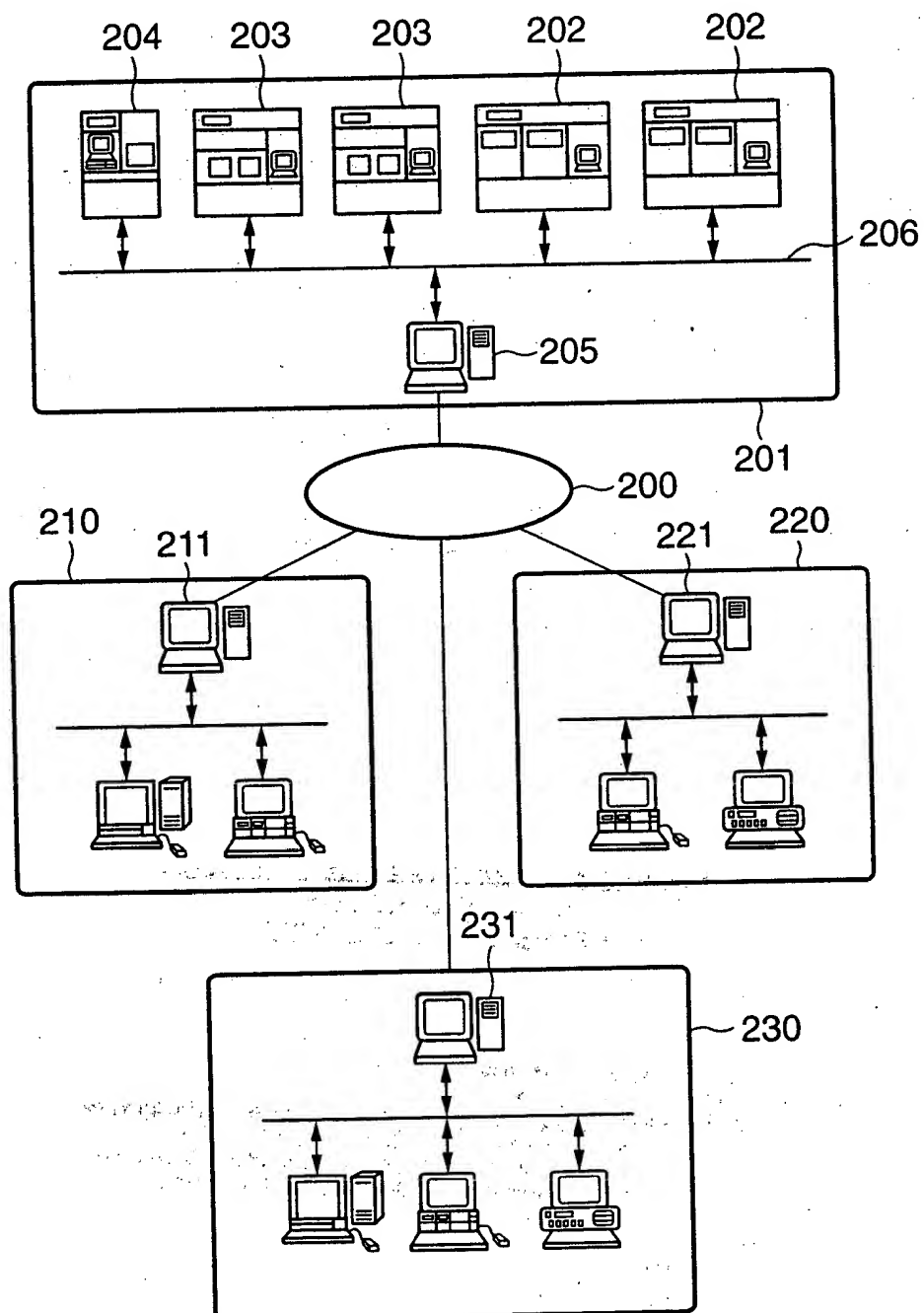


FIG. 12



FOOT-09090000

FIG. 13

URL

MALFUNCTION DATABASE INPUT SCREEN

DATE OF OCCURRENCE ~ 404

MODEL ~ 401

SUBJECT MATTER ~ 403

EQUIPMENT SERIAL NO. ~ 402

DEGREE OF URGENCY ~ 405

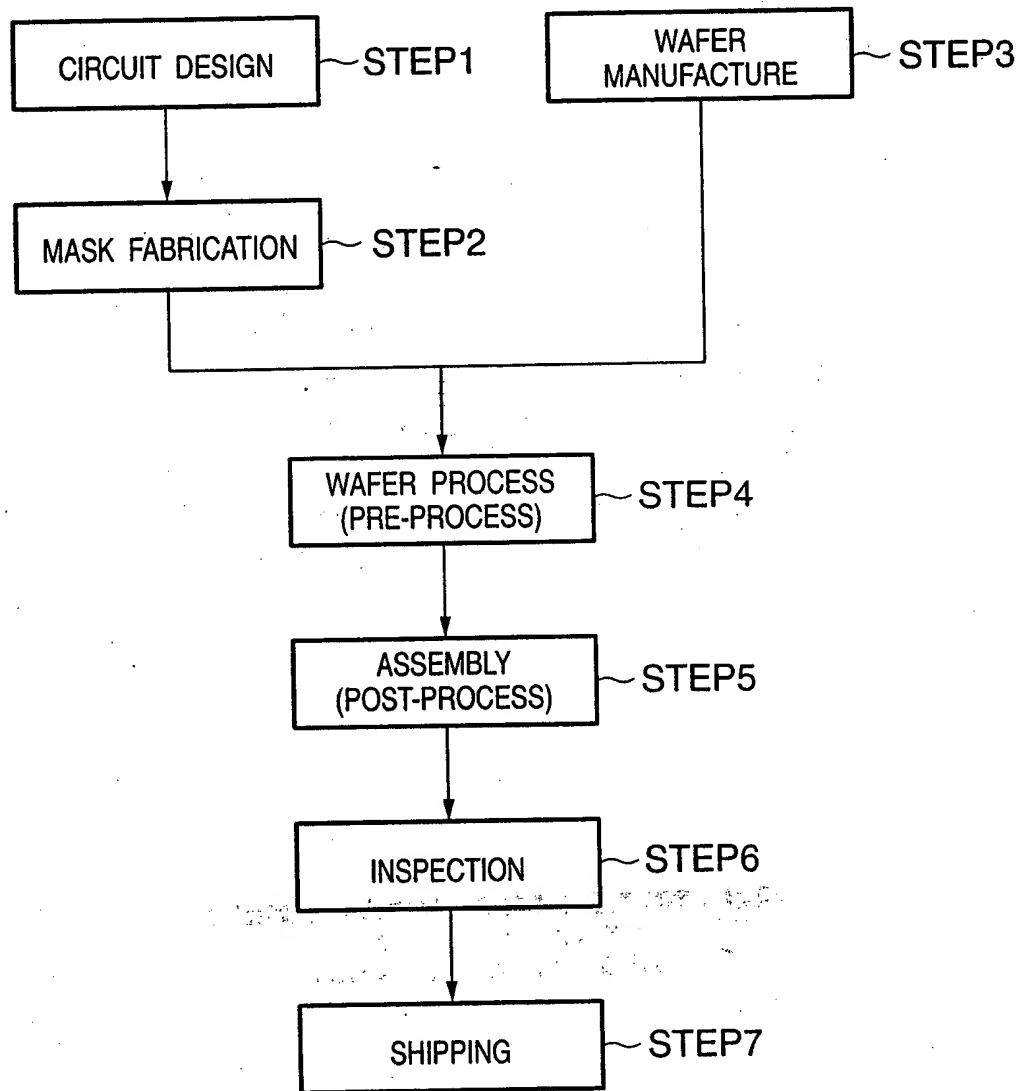
CONDITION ~ 406

COUNTERMEASURE METHOD ~ 407

PROGRESS REPORT ~ 408

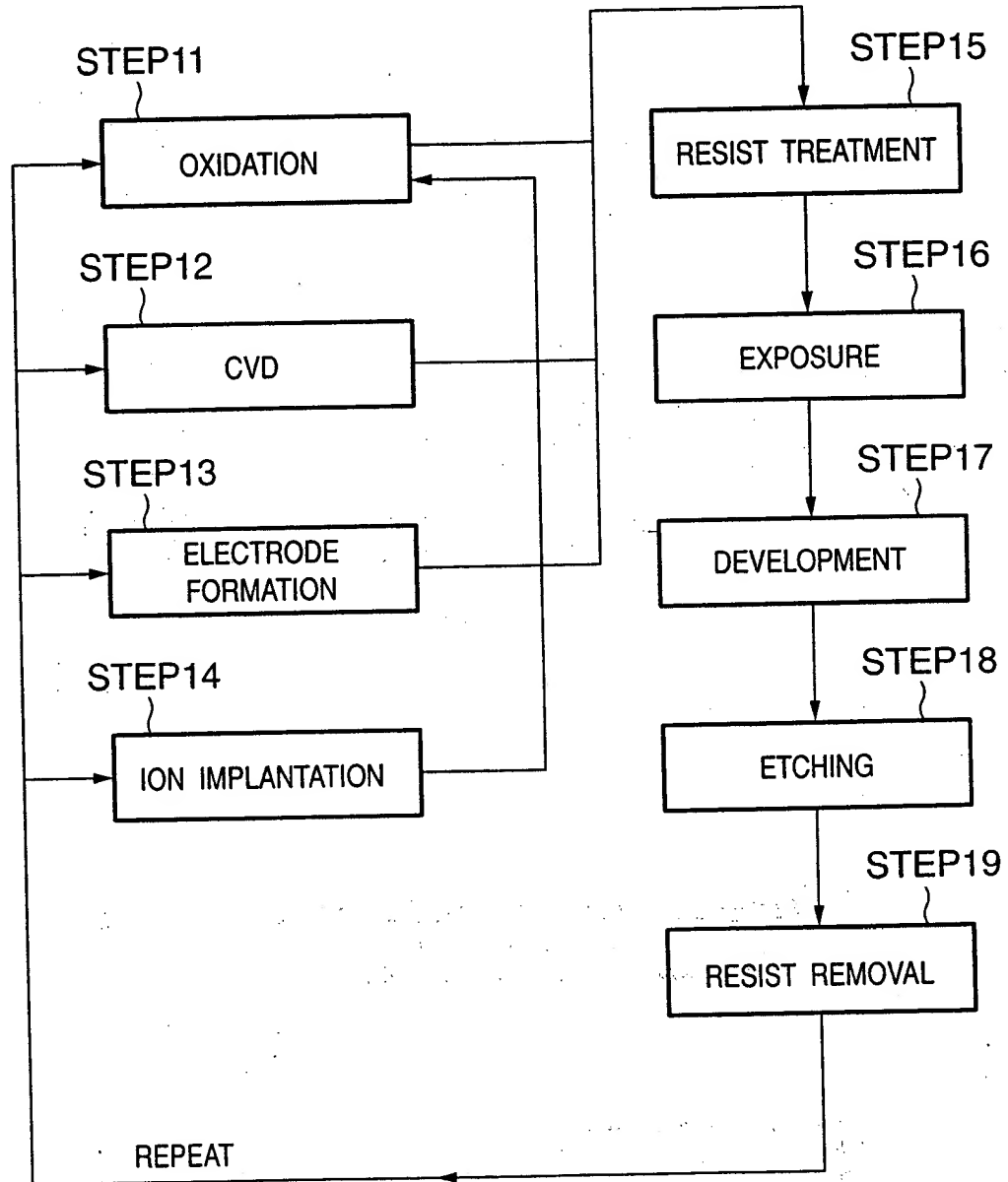
410 411 412

[LINK TO DATABASE OF RESULTS](#) [SOFTWARE LIBRARY](#) [OPERATION GUIDE](#)

FIG. 14

FLOW OF SEMICONDUCTOR DEVICE MANUFACTURE

FIG. 15



WAFER PROCESS